

Statement of Volatility – Dell EMC PowerEdge R440

Dell EMC PowerEdge R440 contains both volatile and non-volatile (NV) components. Volatile components lose their data immediately upon removal of power from the component. Non-volatile components continue to retain their data even after the power has been removed from the component. Components chosen as user-definable configuration options (those not soldered to the motherboard) are not included in the Statement of Volatility. Configuration option information (pertinent to options such as microprocessors, remote access controllers, and storage controllers) is available by component separately. The following NV components are present in the PowerEdge R440 server.

ltem	Non-Volatile or Volatile	Quantity	Reference Designator	Size	
Planer					
PCH Internal CMOS RAM	Non-Volatile	1	U_PCH1	256 Bytes	
BIOS SPI Flash	Non-Volatile	1	U_PRIM_SPI_BIOS	32 MB	
BIOS Recovery SPI Flash	Non-Volatile	1	U_RECROM	16 MB	
iDRAC SPI Flash	Non-Volatile	1	U_UBOOT	4 MB	
BMC EMMC	Non-Volatile	1	U_EMMC1	8 GB	
System CPLD RAM	Volatile	1	U_CPLD1	16 KB	
System Memory	Volatile	Up to 10 for CPU1	CPU1: A1~A10,	Up to 32GB per DIMM (RDIMM)	
		Up to 6 for CPU2	CPU2: B1~B6	Up to 64GB per DIMM (LRDIMM)	
Internal USB Key	Non-Volatile	1	J_USB3_INT	Varies (not factory installed)	
Trusted Platform Module (TPM, TPM 2.0 only)	Non-Volatile	1	J_TPM_MODULE	128 Bytes	
CPU Vcore and VSA Regulators	Non-Volatile	1 for CPU1, 1 for CPU2	PAAU1 PBAU1	16KB	
Memory VDDQ Regulators	Non-Volatile	2 for CPU1, 2 for CPU2	PAEU2, PAFU2 PBEU2, PBFU2	16KB	
LOM NVRAM	Non-Volatile	1	U_LOM1_ROM	1 MB	
Power Supplies	Power Supplies				
Microcontroller	Non-Volatile	Up to 2	Microchip	Up to 64KB	

Item	Non-Volatile or Volatile	Quantity	Reference Designator	Size		
1U 4x3.5" Backplane	1U 4x3.5" Backplane					
SEP internal flash	Non-Volatile	1	U_SEP	Flash:32KB EEPROM:2KB		
1U 8x2.5" Backplane						
SEP internal flash	Non-Volatile	1	U_SEP	Flash:32KB EEPROM:2KB		
1U 10x2.5" EXP/Back	olane					
NVSRAM memory	Non-Volatile	1	U3	MRAM: 1 Mb EEPROM:2KB		
Flash memory	Non-Volatile	1	U2	Flash: 128 Mb		
BP FRU image	Non-Volatile	1	U14	EEPROM:2KB		
Expander FRU image	Non-Volatile	1	U5	EEPROM:2KB		
H740, H740P, H840 PE	RC					
NVSRAM memory	Non-Volatile	1	U1087	128KB		
FRU	Non-Volatile	1	U1019	256B		
SPD	Non-Volatile	1	U22	256B		
Flash	Non-Volatile	1	U1086	16MB		
Backup Flash	Non-Volatile	1	U1100	8GB		
SDRAM	Volatile	9	U1077-U1085	8GB		
H330 PERC						
NVSRAM memory	Non-Volatile	1	U1033	128KB		
FRU	Non-Volatile	1	U1019	256B		
1-Wire EEPROM	Non-Volatile	1	U1004	128B		
SBR	Non-Volatile	1	U1020	8KB		
Flash	Non-Volatile	1	U3	16MB		
HBA 330 PERC						
NVSRAM memory	Non-Volatile	1	U1033	128KB		
FRU	Non-Volatile	1	U1019	256B		
Serial Boot ROM	Non-Volatile	1	U1020	8KB		
Flash	Non-Volatile	1	U3	16MB		
Left (Quick Sync 2.0 module) Ear						

Item	Non-Volatile or Volatile	Quantity	Reference Designator	Size
MCU	Non-Volatile	1	USAM7	32Mb
Left (status) Ear				
MCU	Non-Volatile	1	U_TINY	8KB
Right Ear				
SPI Flash	Non-Volatile	1	U2	32Mb
ТРМ				
Trusted Platform Module (TPM, TPM 2.0 only)	Non-Volatile	1	U_TPM	128 Bytes
IDSDM - vFlash	I	I		
vFlash (uSD)	Non-Volatile	1	J3	16GB
iDSDM (uSD1, uSD2)	Non-Volatile	2	J1, J2	16GB, 32GB, 64GB
SPI Flash	Non-Volatile	1	U2	1MB
BOSS	I	I		
SPI Flash	Non-Volatile	1	U17	1024KB
TFRU	Non-Volatile	1	U7	64КВ
LCD Bezel				
Microcontroller	Non-Volatile	1	IC1	256KB

Item	Type (e.g. Flash PROM, EEPROM)	Can user programs or operating system write data to it during normal operation?	Purpose? (e.g. boot code)
Planer			
PCH Internal CMOS RAM	Battery-backed CMOS RAM	No	Real-time clock and BIOS configuration settings
BIOS SPI Flash	SPI Flash	Yes	Boot code, system configuration information, UEFI environment, Flash Disceptor, ME
BIOS Recovery SPI Flash	SPI Flash	No	16MB Recovery SPI ROM exits as an aid to reprogram the primary ROM
iDRAC SPI Flash	SPI Flash	No	iDRAC Uboot (bootloader), server managent persistent store (i.e. IDRAC MAC Address, iDRAC boot variables), lifecycle log cache, virtual planar FRU and EPPID, rac log, System Event Log,
BMC EMMC	eMMC NAND Flash	No	Operational iDRAC FW, Lifecycle Controller (LC) USC partition, LC service diags, LC OS drivers, USC firmware
Memory VDDQ, CPU Vcore and VSA Regulators	OTP(one time programmable)	No	Operational parameters
System CPLD RAM	RAM	No	Not utilized
System Memory	RAM	Yes	System OS RAM
Internal USB Key	Flash	Yes	General purpose USB key drive
Trusted Platform Module (TPM, TPM 2.0 only)	EEPROM	Yes	Storage of encryption keys
Power Supplies			
Microcontroller	Flash PROM and EEPROM	Yes	Report PSU information and control firmware
1U 4x3.5" Backplane			
SEP internal flash	Flash	No	FW configuration data

Item	Type (e.g. Flash PROM, EEPROM)	Can user programs or operating system write data to it during normal operation?	Purpose? (e.g. boot code)
SEP internal EEPROM	EEPROM	No	FRU
1U 8x2.5" Backplane		I	
SEP internal flash	Flash	No	FW configuration data
SEP internal EEPROM	EEPROM	No	FRU
1U 10x2.5" EXP/Backplan	e	I	1
NVSRAM memory	MRAM	No	Configuration data
Flash memory	Flash	No	Card firmware
BP FRU image	EEPROM	No	FRU
Expander FRU image	EEPROM	No	FRU
H740, H740P, H840 PERC			
NVSRAM memory	NVSRAM	No	Configuration data
FRU	FRU	No	Card manufacturing information
SPD	SPD	No	Memory configuration data
Flash	Flash	No	Card firmware
Backup Flash	Backup Flash	No	Holds cache data during power loss
SDRAM	SDRAM	No	Cache for HDD I/O
H330 PERC			
NVSRAM memory	NVSRAM	No	Configuration data
FRU	FRU	No	Card manufacturing information
1-Wire EEPROM	1-Wire EEPROM	No	Holds default controller properties/settings
SBR	SBR	No	Boot loader
Flash	Flash	No	Card firmware
HBA 330 PERC			

Item	Type (e.g. Flash PROM, EEPROM)	Can user programs or operating system write data to it during normal operation?	Purpose? (e.g. boot code)
NVSRAM memory	NVSRAM	No	Configuration data
FRU	FRU	No	Card manufacturing information
Serial Boot ROM	Serial Boot ROM	No	Boot loader
Flash	Flash	No	Card firmware
Left (Quick Sync 2.0 module	e) Ear		
MCU	embedded Flash	No	Card firmware
Left (status) Ear			
MCU	embedded Flash	No	Card firmware
Right Ear			
SPI Flash	SPI Flash	No	For field maintenance. Have License, Service Tag and system information.
ТРМ	.	-	
Trusted Platform Module (TPM, TPM 2.0 only)	EEPROM	Yes	Storage of encryption keys
IDSDM - vFlash			
vFlash (uSD)	NAND flash	Yes	Populate out-of-band or optionally connect to the host as mass storage and boot mechanism
iDSDM (uSD1, uSD2)	NAND flash	Yes	Provides mass storage
SPI Flash	SPI Flash	It is only indirectly connected to iDRAC. iDRAC can read any address in the SPI flash, but may only write the primary firmware storage area as a part of a firmware update procedure.	Boot firmware storage, configuration and state data for IDSDM.
BOSS		I	

Item	Type (e.g. Flash PROM, EEPROM)	Can user programs or operating system write data to it during normal operation?	Purpose? (e.g. boot code)
SPI Flash	FLASH EEPROM	No	Boot code, FW
TFRU	FLASH EEPROM	Yes	Thermal monitoring
LCD Bezel			
Microcontroller	Internal Flash	No	Boot loader and s/w implementation of LCD command set

Item	How is data input to this	How is this memory write	How is the memory
	memory?	protected?	cleared?
Planer			
PCH Internal CMOS RAM	BIOS	N/A – BIOS only control	 Set NVRAM_CLR jumper to clear BIOS configuration settings at boot and reboot system. Power off the system, remove coin cell battery for 30 seconds, replace battery and then power back on. Restore default configuration in F2 system setup menu.
BIOS SPI Flash	SPI interface via iDRAC	Software write protected	Not possible with any utilities or applications and system is not functional if corrupted or removed.
BIOS Recovery SPI Flash	SPI interface via PCH	Software write protected	Not possible with any utilities or applications and the system is not functional if BIOS SPI is corrupted or removed.
iDRAC SPI Flash	SPI interface via iDRAC	Embedded iDRAC subsystem firmware actively controls sub area based write protection as needed.	The user cannot clear memory completely. However, user data, lifecycle log and archive, SEL, and fw image repository can be cleared using Delete Configuration and Retire System, which can be accessed through the Lifecycle Controller interface.
BMC EMMC	NAND Flash interface via iDRAC	Embedded FW write protected	The user cannot clear memory completely. However, user data, lifecycle log and archive, SEL, and fw image repository can be cleared using Delete Configuration and Retire System, which can be accessed through the Lifecycle Controller interface.
Memory VDDQ, CPU Vcore and VSA Regulators	Once values are loaded into register space a cmd writes to nvm.	There are passwords for different sections of the register space	The user cannot clear memory.
System CPLD RAM	Not utilized	Not accessible	Not accessible
System Memory	System OS	OS Control	Reboot or power down

Item	How is data input to this memory?	How is this memory write protected?	How is the memory cleared?
			system
Internal USB Key	USB interface via PCH. Accessed via system OS	No write protect	Can be cleared in the system OS
Trusted Platform Module (TPM, TPM 2.0 only)	Using TPM Enabled operating systems	SW write protected	F2 Setup option
Power Supplies			
Microcontroller	The data is flash via Dell Update Package(DUP)	Using signature and manufacture key to protect memory write	Before firmware update, the memory will be clear.
1U 4x3.5" Backplane			
SEP internal flash	Pre-programmed before assembly	Not WP	The user cannot clear memory.
SEP internal EEPROM	Programmed at ICT during production.	Not WP	The user cannot clear memory.
1U 8x2.5" Backplane			
SEP internal flash	Pre-programmed before assembly	Not WP	The user cannot clear memory.
SEP internal EEPROM	Programmed at ICT during production.	Not WP	The user cannot clear memory.
1U 10x2.5" EXP/Backplane	•	I	
NVSRAM memory	ROC writes configuration data to NVSRAM	Not WP. Not visible to Host Processor	Cannot be cleared with existing tools available to the customer
Flash memory	Pre-programmed before assembly. Can be updated using Dell/LSI tools	Not WP. Not visible to Host Processor	Cannot be cleared with existing tools available to the customer
BP FRU image	Programmed at ICT during production.	Not WP	The user cannot clear memory.
Expander FRU image	Programmed at ICT during production.	Not WP	The user cannot clear memory.
H740, H740P, H840 PERC			
NVSRAM memory	ROC writes configuration data to NVSRAM	Not WP. Not visible to Host Processor	User cannot clear the memory.
FRU	Programmed at ICT during production.	Not WP	User cannot clear the memory.
SPD	Pre-programmed before assembly	Not WP. Not visible to Host Processor	User cannot clear the memory.
Flash	Pre-programmed before assembly. Can be updated using Dell/LSI tools	Not WP. Not visible to Host Processor	User cannot clear the memory.
Backup Flash	FPGA backs up DDR data	Not WP. Not visible to	Flash can be cleared by

memory? to this device in case of a power failure	Host Processor	powering up the card and allowing the controller to flush the contents to VDs. If the VDs are no longer available, cache can be
power failure		flush the contents to VDs. If the VDs are no longer
		If the VDs are no longer
		•
		available, cache can be
		cleared by going into
		controller BIOS and
		selecting Discard
		Preserved Cache.
ROC writes to this	Not WP. Not visible to	Cache can be cleared by
memory - using it as cache for data IO to HDDs	Host Processor	powering off the card
ROC writes configuration	Not WP. Not visible to	Cannot be cleared with
data to NVSRAM	Host Processor	existing tools available to
		the customer
Programmed at ICT during	Not WP	Cannot be cleared with
production.		existing tools available to
		the customer
ROC writes data to this	Not WP. Not visible to	Cannot be cleared with
memory	Host Processor	existing tools available to
		the customer
Pre-programmed before	Not WP. Not visible to	Cannot be cleared with
assembly	Host Processor	existing tools available to
		the customer
Pre-programmed before	Not WP. Not visible to	Cannot be cleared with
assembly. Can be updated	Host Processor	existing tools available to
using Dell/LSI tools		the customer
ROC writes configuration	No write protect. Not	The user cannot clear
data to NVSRAM	visible to Host Processor	memory.
Programmed at ICT during	No write protect	The user cannot clear
•		memory.
	-	The user cannot clear
assembly	visible to Host Processor	memory.
Pre-programmed before	No write protect. Not	The user cannot clear
		memory.
		memory.
Pre-programmed before	N/Δ	The user cannot clear
assembly		memory.
Pre-programmed before	N/A	The user cannot clear
assembly		memory.
SPI interface via iDRAC	Hardware strapping	The user cannot clear
		memory.
	for data IO to HDDs ROC writes configuration data to NVSRAM Programmed at ICT during production. ROC writes data to this memory Pre-programmed before assembly. Can be updated using Dell/LSI tools ROC writes configuration data to NVSRAM Programmed at ICT during production Pre-programmed before assembly. Can be updated using Dell/LSI tools Far Pre-programmed before assembly. Can be updated using Dell/LSI tools Far Pre-programmed before assembly. Can be updated using Dell/LSI tools Far Pre-programmed before assembly. Can be updated using Dell/LSI tools	for data IO to HDDsROC writes configuration data to NVSRAMNot WP. Not visible to Host ProcessorProgrammed at ICT during production.Not WPROC writes data to this memoryNot WP. Not visible to Host ProcessorPre-programmed before assembly. Can be updated using Dell/LSI toolsNot WP. Not visible to Host ProcessorROC writes configuration data to NVSRAMNot WP. Not visible to Host ProcessorPre-programmed before assembly. Can be updated using Dell/LSI toolsNot write protect. Not visible to Host ProcessorProgrammed at ICT during productionNo write protect. Not visible to Host ProcessorPre-programmed before assemblyNo write protect. Not visible to Host ProcessorPre-programmed before assemblyNo write protect. Not visible to Host ProcessorPre-programmed before assembly. Can be updated using Dell/LSI toolsNo write protect. Not visible to Host ProcessorPre-programmed before assembly. Can be updated using Dell/LSI toolsNo write protect. Not

Item	How is data input to this memory?	How is this memory write protected?	How is the memory cleared?
ТРМ			
Trusted Platform Module (TPM, TPM 2.0 only)	Using TPM Enabled operating systems	SW write protected	F2 Setup option
IDSDM - vFlash			
vFlash (uSD)	User can provide data to iDRAC (entirely in the iDRAC domain) to be pushed into vFlash	No write protect	1. The card may be physically removed and destroyed or cleared via standard means on a separate computer. Or 2. The user has access to the card in the host domain and may clear it manually.
iDSDM (uSD1, uSD2)	Device resides in host domain; they are exposed to the user via an internally connected, non- removable USB mass storage device	Physical write protect switch on ACE card	 (1) card may be physically removed and destroyed or cleared via standard means on a separate computer OR (2)User has access to the card in the host domain and may clear it manually
SPI Flash	User can initiate a firmware update of the IDSDM device.	There is no mechanism provided to iDRAC to write any SPI NOR area outside of the primary IDSDM firmware region.	iDRAC may issue a clear command to erase all contents of the SPI NOR, but doing this will leave the IDSDM non-functional.
BOSS			
SPI Flash	By programming the image via firmware update process	N/A	Use Flash tool, type "go.nsh w y"
TFRU	During Manufacturing, by programming the image via firmware update process. During runtime, by I2C Proprietary Command Protocol	N/A	By writing to Flash
LCD Bezel			
Microcontroller	Updated as part of secure iDRAC software update. Configuration parameters can change only as part of iDRAC update	Writes are only allowed as part of secure iDRAC update	not user clearable.

NOTE: For any information that you may need, direct your questions to your Dell Marketing contact.

© 2018 Dell Inc.

Trademarks used in this text: Dell[™], the DELL logo, and PowerEdge[™] are trademarks of Dell Inc.